

Claims

[c1] What is claimed is:

1. For a semiconductor manufacturing device, a wafer holder comprising:
a substrate having a wafer-carrying side; and
a substrate-supporting shaft joined to said substrate such that a distance a between the center axis of said shaft and the axial center of said wafer-carrying side of said substrate is 5% or less of the diameter L of the wafer-carrying side.

[c2] 2. A wafer holder as set forth in claim 1, being a ceramic susceptor including at least a resistive heating element.

[c3] 3. A semiconductor manufacturing device in which a wafer holder as set forth in claim 1 is installed.

[c4] 4. A semiconductor manufacturing device in which a wafer holder as set forth in claim 2 is installed.